



Material Content Data Sheet



Sales Product Name		BSO604NS2		Issued		19. January 2018		
MA#		MA001651162						
Package		PG-DSO-8-25		Weight*		83.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.327	3.98	3.98	39792	39792
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		107	
	non noble metal	zinc	7440-66-6	0.036	0.04		429	
	non noble metal	iron	7439-89-6	0.717	0.86		8577	
wire	non noble metal	copper	7440-50-8	29.121	34.83	35.74	348277	357390
	noble metal	gold	7440-57-5	0.417	0.50	0.50	4989	4989
	encapsulation	organic material	carbon black	1333-86-4	0.095	0.11		1134
plastics	plastics	epoxy resin	-	4.363	5.22		52177	
	inorganic material	silicondioxide	60676-86-0	42.964	51.38	56.71	513832	567143
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9733	9733
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7777	7777
glue	plastics	epoxy resin	-	0.193	0.23		2306	
	noble metal	silver	7440-22-4	0.909	1.09	1.32	10870	13176
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com